

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	13	etch adj bath same plating adj bath	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/07/12 14:27
L2	6	etch with plating with bath same semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/07/12 14:28
L3	5	etch with plate with bath same semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/07/12 14:28
L4	551	etch with plate same semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/07/12 14:29
L5	117	etch with plate same semiconductor adj wafer	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/07/12 14:30
L6	2	etch with plate same semiconductor adj wafer same bath	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/07/12 14:31
L7	11	etch same plate same semiconductor adj wafer same bath	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/07/12 14:38
L8	249	etch with plate with semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/07/12 14:40
L9	8	wet adj etch with plate with semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/07/12 14:40

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L7	11	etch same plate same semiconductor adj wafer same bath	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/07/12 14:38
L8	249	etch with plate with semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/07/12 14:40
L9	8	wet adj etch with plate with semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/07/12 14:42
L10	1	("6337030").PN.	USPAT	OR	OFF	2005/07/12 14:55
L11	98	wafer same processing same bath same (plate or plating)	USPAT	OR	OFF	2005/07/12 14:55